	Hits	Search Text	DBs
2	13	((substrate or wafer or device or plate) same ((spray$3 near9 coat$4) or (nozzle near12 spray$3) or dispens$5) same (photoresist or resist or polymide or cur$4) same solution same (coat$3 or film or form$3 or deposit$4)) and ((substrate or wafer or platen or device) same surface same (prim$2 or (treat$5 near6 solution) or treat$4 or pre$3treat$4) same (nozzle or spray or dispens$4) same (rotat$$ or mov$5 or spin$4) same (speed or rate or velocit$4) same (vary$4 or different or chang$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
3	147	((substrate or wafer or device or plate) same ((spray$3 near9 coat$4) or (nozzle near12 spray$3) or dispens$5) same (photoresist or resist or polymide or cur$4) same solution same (coat$3 or film or form$3 or deposit$4)) and ((substrate or wafer or platen or device) same surface same (prim$2 or (treat$5 near6 solution) or treat$4 or pre$3treat$4) same (nozzle or spray or dispens$4) same (rotat$4 or mov$5 or spin$4)) and ((substrate or wafer) same (rotat$4 or spin$4 or mov$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
4	22	((substrate or wafer or device or plate) same ((spray$3 near9 coat$4) or (nozzle near12 spray$3) or dispens$5) same (photoresist or resist or polymide or cur$4) same solution same (coat$3 or film or form$3 or deposit$4)) and ((substrate or wafer or platen or device) same surface same (prim$2 or (treat$5 near6 solution) or treat$4 or pre$3treat$4) same (nozzle or spray or dispens$4) same (rotat$4 or mov$5 or spin$4)) and ((substrate or wafer) same (rotat$4 or spin$4 or mov$5)) and ((photoresist or resist) same negative same positive) and ((substrate or wafer or device) same (resist or photoresist) same uniform$4 same (surface or topograph$6 or film or layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
5	7	((substrate or wafer or device or plate) same ((spray$3 near9 coat$4) or (nozzle near12 spray$3) or dispens$5 or discharg$4) same (photoresist or resist or polymide or cur$4) same solution same (coat$3 or film or form$3 or deposit$4)) and ((substrate or wafer or platen or device) same surface same (prim$2 or (treat$5 near6 solution) or treat$4 or pre$3treat$4) same (nozzle or spray or dispens$4) same (rotat$4 or mov$5 or spin$4) same (speed or rate) same (var$5 or rang$3 or adjust$4)) and ((substrate or wafer) same (rotat$4 or spin$4 or mov$5)) and (contact near16 angle) and (ambient or atmosphere or air or humid$4 or environment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
6	7	((substrate or wafer or device or plate) same ((spray$3 near9 coat$4) or (nozzle near12 spray$3) or dispens$5) same (photoresist or resist or polymide or cur$4) same solution same (coat$3 or film or form$3 or deposit$4)) and ((substrate or wafer or platen or device) same surface same (prim$2 or (treat$5 near6 solution) or treat$4 or pre$3treat$4) same (nozzle or spray or dispens$4) same (rotat$4 or mov$5 or spin$4)) and ((substrate or wafer) same (rotat$4 or spin$4 or mov$5)) and ((resist or photoresist) same (cycl$4hexanone or (propylene near9 glycol)) same (ketone or methyl$4ethyl$4ketone))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
7	2	(("6174561") or ("5762708")).PN.	US-PGPUB; USPAT

	Hits	Search Text	DBs
8	85	((substrate or wafer or device or plate) same ((spray$3 near9 coat$4) or (nozzle near12 spray$3) or dispens$5 or discharg$4) same (photoresist or resist) same solution same solvent same (coat$3 or film or form$3 or deposit$4) saem (deep or micron or feature)) and ((substrate or wafer or platen or device) same surface same (prim$2 or (treat$5 near6 solution) or treat$4 or pre$3treat$4) same (nozzle or spray or dispens$4 or discharg$4) same (rotat$4 or mov$5 or spin$4) same (solvent or solution)) and ((substrate or wafer) same (rotat$4 or sin$4 or mov$5)) and ((resist or photoresist) same (negative or positive))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
9	1	((substrate or wafer) same ((spray$3 near9 coat$4) or (nozzle near12 spray$3) or dispens$5 or discharg$4) same (photoresist or resist) same (coat$3 or form$3 or deposit$4) same (deep or micron or feature or pattern or via or trench)) and ((substrate or wafer or platen or device) same surface same (prim$4 or (treat$5 near6 solution) or treat$4 or pre$3treat$4) same (nozzle or spray or dispens$4 or discharg$4) same (rotat$4 or mov$5 or spin$4) same (solvent or solution)) and ((substrate or wafer) same (rotat$4 or spin$4 or mov$5)) and peroxide$9sul$2ric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
10	2	((substrate or wafer) same ((spray$3 near9 coat$4) or (nozzle near12 spray$3) or dispens$5 or discharg$4) same (photoresist or resist) same (coat$3 or form$3 or deposit$4)) and ((substrate or wafer or platen or device) same surface same (prim$4 or (treat$5 near6 solution) or treat$4 or pre$3treat$4) same (nozzle or spray or dispens$4 or discharg$4) same (rotat$4 or mov$5 or spin$4)) and ((substrate or wafer) same (rotat$4 or spin$4 or mov$5)) and peroxide$9sul$2ric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
11	4	((substrate or wafer or platen or device) same surface same (prim$4 or (treat$5 near6 solution) or treat$4 or pre$3treat$4) same (nozzle or spray or dispens$4 or discharg$4) same (rotat$4 or mov$5 or spin$4)) and ((substrate or wafer) same (rotat$4 or spin$4 or mov$5)) and peroxide$9sul$2ric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
12	103	((substrate or wafer or device or plate) same ((spray$3 near9 coat$4) or (nozzle near12 spray$3) or dispens$5) same (photoresist or resist or polymide or cur$4) same solution same (coat$3 or film or form$3 or deposit$4)) and ((substrate or wafer or platen or device) same surface same (prim$2 or (treat$5 near6 solution) or treat$4 or pre$3treat$4) same (nozzle or spray or dispens$4) same (rotat$4 or mov$5 or spin$4)) and ((substrate or wafer) same (rotat$4 or sin$4 or mov$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
13	54	((substrate or wafer or device or plate) same ((spray$3 near9 coat$4) or (nozzle near12 spray$3) or dispens$5 or discharg$4) same (photoresist or resist) same (coat$3 or film or form$3 or deposit$4)) and ((nozzle or spray) near22 (moving or rotat$4 or spin$4) same uniform$3 same (photoresist or resist)) and negative and positive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
14	0	((substrate or wafer or platen or device) same clean$4 same $4peroxide$9sul$2ric same (immers$4 or dip$4 or solution) same (time or rate or period) same ((rins$4 or spray$4) near16 water near16 (time or period or rate)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
15	0	((substrate or wafer or platen or device) same clean$4 same $4peroxide$9sul$2ric same (immers$4 or dip$4 or solution) same (time or rate or period)) and ((substrate or wafer or device or platen) same ((rins$4 or spray$4) near16 water near16 (time or period or rate)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
16	8	((substrate or wafer or platen or device) same clean$4 same $4peroxide$9sul$2ric same (immers$4 or dip$4 or solution) same (time or rate or period or minutes)) and ((substrate or wafer or device or platen) same ((rins$4 or spray$4) near16 water near16 (time or period or rate or minutes)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
17	8	((substrate or wafer or platen or device) same clean$4 same $4peroxide$9sul$2ric same (immers$4 or dip$4 or solution) same (time or rate or period or minutes)) and ((substrate or wafer or device or platen) same ((rins$4 or spray$4 or immers$5 or wash$6) near16 water near16 (time or period or rate or minutes)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
18	12	((substrate or wafer or platen or device) same clean$4 same $4peroxide$9sul$2ric same (immers$4 or dip$4 or solution) same (time or rate or period or minutes)) and ((substrate or wafer or device or platen) same (rins$4 or spray$4 or immers$5 or wash$6) same water same (time or period or rate or minutes))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
19	12	((substrate or wafer or platen or device) same clean$4 same $4peroxide$9sul$2ric same (immers$4 or dip$4 or solution) same (time or rate or period or minutes)) and ((rins$4 or spray$4 or immers$5 or wash$6) same water same (time or period or rate or minutes))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
20	12	((substrate or wafer or platen or device) same clean$4 same $4peroxide$9sul$2ric same (immers$4 or dip$4 or solution or wash$4 or bath) same (time or rate or period or minutes)) and ((rins$4 or spray$4 or immers$5 or wash$6) same water same (time or period or rate or minutes))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
21	16	((substrate or wafer or platen or device) same $4peroxide$9sul$2ric same (immers$4 or dip$4 or solution or wash$4 or bath) same (time or rate or period or minutes)) and ((rins$4 or spray$4 or immers$5 or wash$6) same water same (time or period or rate or minutes))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB